

# Application based testing of MEMS devices

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**Kees Revenberg** 





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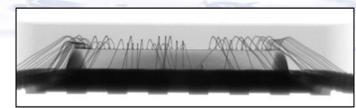
### Introduction

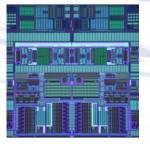
- Independent Test & Diagnostics of Microelectronics
- Failure Analysis services for IC's and electronic components
- Reliability Test services, full product qualification and ESD/LU tests
- Supply Chain consultancy in IC and MEMS back-end manufacturing
- ISO9001 certified and ISO17025 accreditation (RvA L388)
- Founded in 1993, 43 employees (>60% engineering degree)
- 1900m² office & laboratory at Kennispark Enschede, NL
- 5 representations covering EU and IL
- 120+ semiconductor device manufacturers (IDM+fabless)

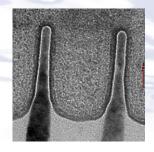


















### MEMS classes

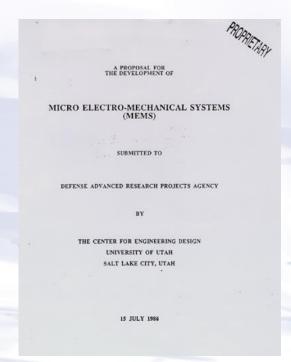
#### → Micro Electrical Mechanical System, since 1986

#### Sensing

- Mechanical → inertial sensing / pressure
- Magnetic → compass
- Optical → image sensors
- Chemical → moisture / chemicals / molecules

### Actuating

- Micromotors quasi-static or free moving
- Microfluid controllers
- Optical switching



Proposal to DARPA by Utah University







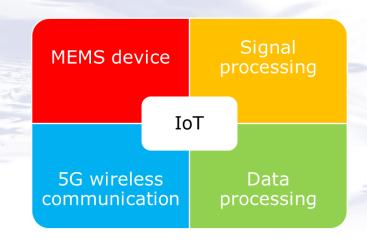
### **MEMS** classes

#### Future Integration of MEMS → IoT applications

- MEMS Signal and Data processing RF communication Power
- Advanced semiconductor processing (<10nm+mixed mode+5G)</li>
- Extension of smart phone: data processing and RF communication
- Autonomous network of MEMS connected to 5G cloud database

### Energy management

- Energy harvesting to power small MEMS
- Ultra low power for >10year battery life
- 24/7 operation for monitoring functions











# **Electrical Test / Physical Test**

- Semiconductor industry production volume test
  - Wafer level E-test → packaging → Final product E-test
- Automated Test Equipment
- Automated wafer handlers
- Parallel device test handlers
- Large OSAT infrastructure
- MEMS industry volume test
  - Only Electrical, no Physical domain



Courtesy Salland Engineering NL

MEMS sensing/actuating conflicts in electrical domain





# **Electrical Test / Physical Test**

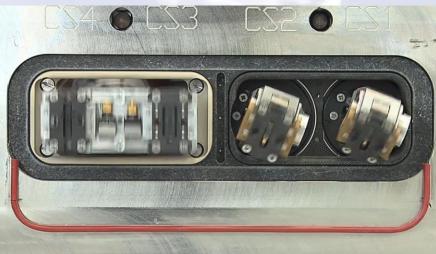
#### MEMS test dilemma

- Volume production with multiple electrical contacts interfere with movements or harsh environmental stresses or optical parameters
- Mechanical / Optical / Chemical stress not available on wafer test
- Package costly part of MEMS

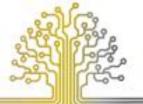
### Current applications

- No or limited wafer test
- Limited OSAT infrastructure
- Low throughput units/min
- Mainly mechanical sensing apps





Courtesy Xcera Corp. USA



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# **MEMS Behavior Analysis**

- Goal: use electrical parameters representing physical MEMS parameter conversion behavior
- Allows MEMS wafer level analysis
  - Faster wafer yield feedback → faster product development cycles
  - Improved test yields and product quality
  - Reduction of costs due to packaging of bad MEMS
- Electrical Characterization under Physical stress
  - Simulation of sensing circuitry response to electrical stimulation
  - Extract electrical parametric behavior to mechanical sensing
  - Extensive characterisation program to prove correlation



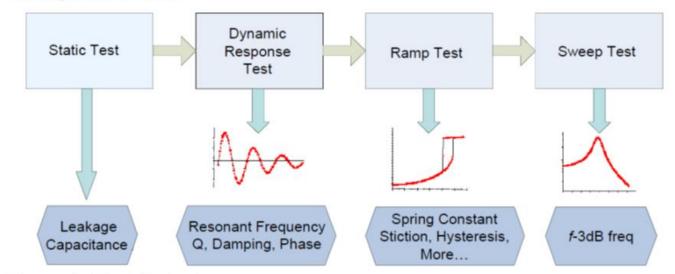




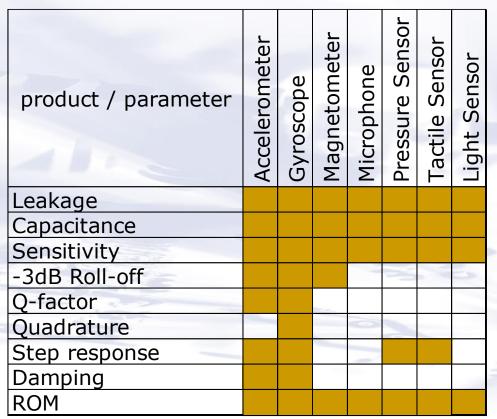
# **Electrical Characterization**

- Many MEMS devices use capacitive change for sensing
- Combined with static I/V
- Dynamic Level testing

#### **Example Test Flow**



**Example Test Output** 



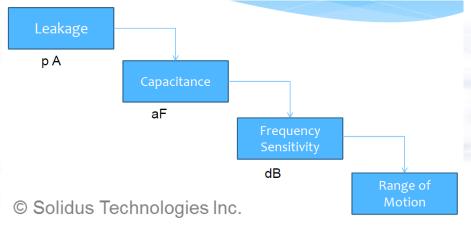


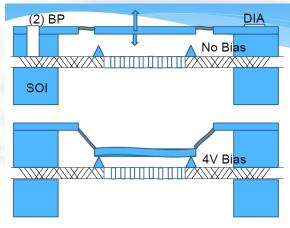


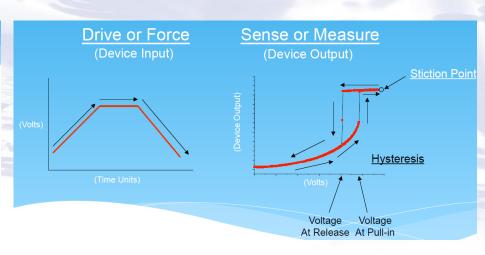


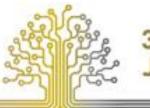
## **Electrical Characterization**

- Example: MEMS microphone wafer level test
- Dedicated measurement tools near probe card
- Range Of Motion test to find potential reliability hazards
- Test flow including I/V, FFT analysis and ROM test









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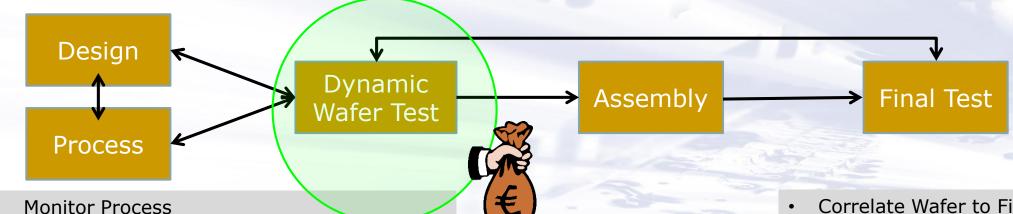


# **Electrical Characterization**

MEMS Manufacturing Value with Dynamic Wafer Test



- Improve Design
- Match Design with Process
- Match Design with Test Performance



- Correlation of Wafer Test to Process
- **Reduce Process Variation**
- Validate Process with Wafer Test Distribution
- Sort for Performance

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- Correlate Wafer to Final Test
- **Reduce Final Test Times**
- Reduce Final Tests
- Improve Final Test Yields
- Increase Units Per Hour

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# **Qualification and Production Test**

- Qualification test procedure
  - Chip/MEMS related stress tests
  - Package related stress tests
  - Physical Construction Analysis
- Real world simulation
  - Tyre pressure sensor @ 230km/h
  - Constant acceleration test
     60 units, 24 hours / axis, 6 axis
  - Electrical monitoring test







# **Qualification and Production Test**

**Integrated Test Solutions on ATE** 

Universal ATE Instrument



Industrialized test solution using custom technology

> "SMART Platform solution" Device Family based



"Add-on Instruments"



**Enhanced Integration** Debugtooling Calibration & diagnostic Supplychain Supports families Robustness



Application Specific

Courtesy: Salland Engineering NL

Technology

Universal



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Cost of Test



# Summary

- MEMS devices are an important class with high growth
- More devices require improvements in the supply chain
- MEMS play an important role in autonomous systems
- New MEMS technology find new application area's
- Dynamic Wafer Level testing is a good novel approach
- Combined with extensive correlation and qualification test this approach offers best in class MEMS devices
- R&D and DfT efforts needed to expand the e-test application during volume production testing





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